

DECLARATION FOR NON-PROVISIONAL PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below at 201 et seq. beneath my name.

I believe I am the original, first and sole inventor if only one name is listed at 201 below, or an original, first and joint inventor if plural names are listed at 201 et seq. below, of the subject matter which is claimed and for which a patent is sought on the invention entitled

**WAFER WITH A RELAXED USEFUL LAYER AND
METHOD OF FORMING THE WAFER**

and for which a patent application is attached hereto.

I hereby state that I have reviewed and understand the contents of the above identified application, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

EARLIEST FOREIGN APPLICATION(S), IF ANY, FILED PRIOR TO THE FILING DATE OF THE APPLICATION			
APPLICATION NUMBER	COUNTRY	DATE OF FILING (day, month, year)	PRIORITY CLAIMED
0211543	France	18 September 2002	<input checked="" type="checkbox"/> YES <input type="checkbox"/> NO
			<input type="checkbox"/> YES <input type="checkbox"/> NO

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below.

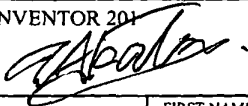
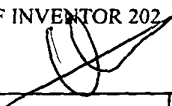
PROVISIONAL APPLICATION NUMBER	FILING DATE
60/439,428	13 January 2003

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code § 112, I acknowledge the duty to disclose information known to me which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application:

NON-PROVISIONAL APPLICATION NO.	FILING DATE	STATUS		
		PATENTED	PENDING	ABANDONED

* for use only when the application is assigned to a company, partnership or other organization.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

201	FULL NAME OF INVENTOR	LAST NAME AKATSU	FIRST NAME Takeshi	MIDDLE NAME	
	RESIDENCE & CITIZENSHIP	CITY St Nazaire Les Eymes	STATE OR FOREIGN COUNTRY France	COUNTRY OF CITIZENSHIP France	
	POST OFFICE ADDRESS	STREET 9, place de l'Eglise	CITY St Nazaire Les Eymes	STATE OR COUNTRY France	ZIP CODE 38330
		SIGNATURE OF INVENTOR 201 		DATE 09/06/03	
202	FULL NAME OF INVENTOR	LAST NAME GHYSELEN	FIRST NAME Bruno	MIDDLE NAME	
	RESIDENCE & CITIZENSHIP	CITY Seyssinet	STATE OR FOREIGN COUNTRY France	COUNTRY OF CITIZENSHIP France	
	POST OFFICE ADDRESS	STREET 58, rue George Maeder	CITY Seyssinet	STATE OR COUNTRY France	ZIP CODE 38170
		SIGNATURE OF INVENTOR 202 		DATE 09/06/03	
203	FULL NAME OF INVENTOR	LAST NAME	FIRST NAME	MIDDLE NAME	
	RESIDENCE & CITIZENSHIP	CITY	STATE OR FOREIGN COUNTRY	COUNTRY OF CITIZENSHIP	
	POST OFFICE ADDRESS	STREET	CITY	STATE OR COUNTRY	ZIP CODE
		SIGNATURE OF INVENTOR 203		DATE	
204	FULL NAME OF INVENTOR	LAST NAME	FIRST NAME	MIDDLE NAME	
	RESIDENCE & CITIZENSHIP	CITY	STATE OR FOREIGN COUNTRY	COUNTRY OF CITIZENSHIP	
	POST OFFICE ADDRESS	STREET	CITY	STATE OR COUNTRY	ZIP CODE
		SIGNATURE OF INVENTOR 204		DATE	
205	FULL NAME OF INVENTOR	LAST NAME	FIRST NAME	MIDDLE NAME	
	RESIDENCE & CITIZENSHIP	CITY	STATE OR FOREIGN COUNTRY	COUNTRY OF CITIZENSHIP	
	POST OFFICE ADDRESS	STREET	CITY	STATE OR COUNTRY	ZIP CODE
		SIGNATURE OF INVENTOR 205		DATE	

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Takeshi AKATSU *et al.* Confirmation No.:
Application No.: Group Art Unit:
Filing Date: Concurrently herewith Examiner:
For: WAFER WITH A RELAXED USEFUL Attorney Docket No.: 4717-8900
LAYER AND METHOD OF FORMING
THE WAFER

**POWER OF ATTORNEY BY ASSIGNEE
AND EXCLUSION OF INVENTOR(S) UNDER 37 C.F.R. 3.71**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

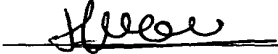
The undersigned assignee of the entire interest in the above-identified subject application hereby appoints Allan A. Fanucci (Reg. No. 30,256) and Daniel J. Hulseberg (Reg. No. 36,554) of WINSTON & STRAWN LLP (Customer No. 28,765) to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith.

Please direct all correspondence for this application to Customer No. 28765 to the attention of Allan A. Fanucci (telephone 212-294-3311, facsimile 212-294-4700).

An assignment of the entire interest in the above-identified subject application:

- ☒ is submitted herewith for recording and a copy is attached.
☐ was submitted for recordation on _____ and a copy is attached.
☐ was recorded on _____ at Reel _____, Frame _____.

The undersigned has reviewed this assignment and, to the best of his/her knowledge, title is in the assignee seeking to take action in this application and that he/she is empowered to act on its behalf.

ASSIGNEE: S.O.I. TEC SILICON ON INSULATOR TECHNOLOGIES S.A.
Signature: 
Date of Signature: 09/12/2003
Typed Name: Emmanuel Huyghe
Position/Title: Intellectual Property Manager
Address: Parc Technologique des Fontaines
38926 Bernin, France